Forward Region Calorimetry

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for the FCAL Collaboration



DESY PRC Meeting 2007

Hamburg November 8th

FCAL Collaboration

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Supported by: >EUROTeV, >EUDET, >NoRHDIA >INTAS >DOE

➢Cooperation with SLAC

Outline

- □ Generel FCAL Overview
- FCAL Detectors: motivation, design concepts and simulations
 - LumiCal
 - BeamCal
 - GamCal
- □ FCAL integration
- Sensors R&D
- Readout Electronics R&D
- ^D Summary

Tasks of Forward Region

 The FCAL Collaboration develops the Very Forward Detectors: LumiCal, BeamCal and GamCal in the Forward region of the ILC, for SID and LDC

IP

5mrad

• Precise measurement of integrated luminosity ($\Delta L/L \ge 10^{-4}$) • Provide 2-photon veto

> Provide 2-photon veto
> Serve beamdiagnostics using beamstrahlung pairs

•Serve beamdiagnostics using beamstrahlung photons

Challenges:

High precision, high occupancy, high radiation dose, fast read-out!

Forward Region Design



LumiCal -Precise Measurement of Luminosity

- Required precision is:
 - $\Delta L/L \sim 10^{-4}$ (GigaZ 10⁹/year)
 - $\Delta L/L < 10^{-3} (e^+e^- \rightarrow W^+W \ 10^6/year)$
 - $\Delta L/L < 10^{-3} (e^+e^- \rightarrow q^+q^- 10^6/year)$



- Bhabha scattering ee-> $ee(\gamma)$ is the gauge process:
 - Count Bhabha event in a well known accepctance region => $L = N/\sigma$
 - High statistics at low angles (N_{Bhabha} ~ 1/θ³) => need about 1 year of running at design luminosity
 - Well known electromagnetic process (LEP: 10⁻³): the current limit on the theoretical cross section error is at ~5 10⁻⁴.

LumiCal: Physics Background and Beam-Beam Effect

- □ 2-photon events are the main background.
- We determined an efficient set of cuts to reduce the background to the level of 10⁻⁴.
- Bhabha Suppression Effect is due to EM deflection and energy loss by beamstrahlung of Bhabhba's..







LumiCal Design

Si/W sandwich calorimeter, 2 half barrels, each 30-40 layers



Half plane - 24 sectors, 96 cylinders (36 silicon tiles, 2304 pads)

Clustering in LumiCal

- 1. Perform initial 2D "Nearest Neighbors" clustering in shower-peak layers.
- Extrapolate "virtual cluster" CMs in non shower-peak layers, and build real clusters accordingly.
- Build (global) 3D "super clusters" from all 2D layer clusters. 3.
- Check cluster properties (longitudinal development), and try to re-cluster.

Electron Photon



Cluster position reconstruction



New LumiCal design concepts



- LumiCal is composed of two components: Silicon Tracker and a Calorimeter.
- □ In this design five silicon tracking layers are used, granulated into concentric strips.
- □ New reconstruction algorithm developed, combining Tracker and Calorimeter info.
- □ Above 90% efficiency of the tracker.
- First results:
 - Significant improvement in polar resolution (factor of 5 10).
 - Improvement in the polar bias (factor of 1.2 3).
- Design optimization study is ongoing (including a pixel tracker version).

LumiCal Position Aligment

Single (L/R) LumiCal alignment Inner radius accuracy $\sim 4\mu m$ л/л ЛГ/Л LumiCal Outgoing θ. 0.012 heam. 0.01 MC simulations LumiCal 0.008 $\frac{\Delta L}{\Delta L} = \frac{\Delta \sigma}{\Delta \theta} \cong 2 \frac{\Delta \theta}{\Delta \theta}$ 0.006 0.004 0.002 LumiCal X, Y position with respect to the α beam should be known with accuracy better 10-4 10-3 than \sim 700 µm (optimal \sim 100 -200 µm) σ_{Θ} (rad) (LumiCal centered on outgoing beam) 4570 mm 200 mm .umiCal шШ .umiCal Two LumiCal's (L,R) alignment Right Left 416 IP Requested accuracy on distance between

150 mm

(active volume shown)

150 mm

two LumiCal's better than ~60 -100 μm (14 mrad crossing angle)

Laser Alignment System



Two laser beams (one perpendicular, second 45° to sensor plane) allow to measure XYZ translation in one sensor





Temperature stability is an issue Observed changes ~ $1 \mu m/1 {}^{0}C$

Works underway on integration of LAS into FCAL system

BeamCal Challenges

BeamCal will extend

the sensitive region to lowest polar angles.

Challenge:
 Detect single high
 energetic particle
 on top of a
 background of 10⁴ low

energetic e⁺e⁻pairs.

BeamCal serves also as part of the beam



 γ μ^{-} 2-p μ^{+} the

Physics signal: e.g. SUSY smuon production

e⁻ Background signal:
 µ⁻ 2-photon event, may fake
 µ⁺ the upper signal if the electron
 e⁺ escapes.



diagnostics system

BeamCal Design



BeamCal: Particle Veto



BeamCal: Veto Efficiency



GamCal Motivation

- Measuring the beam-strahlung pairs and gammas provides robust complementary information
- Ratio of pairs to gammas is largely proportional to instantaneous luminosity

Bethe-Heitler: $\gamma e \rightarrow e \ e^+e^-$



GamCal Design Concept

- 180m from interaction point
- 10⁻⁴ X₀ to convert beam-strahlung gammas into e⁺e⁻ pairs
- Dipole magnet
 separates the pairs
 from beam electrons
- Calorimeters measure the 1-10 GeV positrons
- Design currently under study

BVEX2G YSWEER 0.417 IL AT A LE AL AT A LE в. 10GeV Foil 188 190 192 200 202 204 206 208 196 eam electrons strahlung gamma's ositrons produced at foil ungsten/guartz sandwich

Integrated Beamstrahlung Spectrometer

FCAL Integration



Works on FCAL mechanical integration in progress...

BeamCal: Radiation Hard Sensor Materials

- The load from low energetic pairs from beamstrahlung on the BeamCal will be very high, ~10⁵ e⁺e⁻ pairs, depositing about 10TeV per bunch crossing. This corresponds to a dose of several MGy per year (several 100 Mrads per year !!!).
- We consider several sensor materials:
 - CVD diamond sensors
 - GaAs sensors
 - SiC
 - radiation hard Si



-z BeamCal

Materials under Investigation

pCVD diamonds:

- radiation hardness under investigation (e.g. LHC pixel detectors)
- advantageous properties like: high mobility, low ε_R = 5.7, thermal conductivity
- availability on wafer scale

GaAs:

- semi-insulating GaAs, doped with Sn and compensated by Cr
- produced by the Siberian Institute of Technology
- * available on (small) wafer scale

sCVD diamonds:

- available in sizes of mm²
- Rad-hard Si (just starting)





- Samples from two manufacturers:
 ◆Element Six_™
 ◆Fraunhofer Institute for Applied Solid-State Physics – IAF
- > 1 x 1 cm²
- 200-900 µm thick (typical thickness 300µm)
 Ti(/Pt)/Au metallization



>500 µm thick detector, 87 5x5 mm pads
 > Mounted on a 0.5 mm PCB with fanout
 > Metallization is V (30 nm) + Au (1 µm)
 > Works as a solid state ionization chamber
 > structure is provided by metallization

≻scCVD diamond ≻area 5x5 mm2, thickness 340 μm,

metallization Ø3mm



CCD & other Measurements

CCD = Charge Collection Distance

= mean drift distance of the charge carriers = $Q_{meas}/Q_{induced}$ x thickness



ADC Channels ~ charge

Other measurements showing sensor performance:

- Depletion voltage, from capacitance vs bias voltage measurement (C-V)
- Leakage current, measured as a function of bias voltage (I-V)

High Dose Irradiation

Superconducting DArmstadt LINear ACcelerator Technical University of Darmstadt







- Irradiation up to several MGy:
 10 ± 0.015 MeV and beam currents from 10 to
 50 nA corresponding to 60 to 300 kGy/h.
- Keeping the sensor under bias permanently.
- This is a much higher dose rate compared to the application at the ILC (~1 kGy/h)

 $(1 \text{ MGy} = 100 \text{ Mrad is deposited by about} 4 \times 10^{15} \text{ e}^{-7} \text{ cm}^2)$

Irradiation of GaAs



Polycrystalline CVD Diamond

After absorbing 5-6 MGy:

CVD diamonds still operational.

E6 samples CCD vs dose at 400V 200 CCD [µm] E6 B1 180 E6 B3 160 decrease 140 * * ¥ _{***} _{**} 120 100 pumping 80 depumping 60 bv UV 40 20 0[∟]0 3000 1000 2000 4000 5000 6000 Dose [kGy]



Very low leakage currents (~pA)
 Decrease of CCD
 Generation of trapping centers

Single Crystal CVD Diamond



Reduction of measured signal, but still operating after 5 MGy. (~340µm thickness)

Sensors for LumiCal

- No radiation problem
- Standard silicon
- Possible candidade (Hamamatsu)
 - Si wafer thickness = 320 μm
 - Dark current ~ 10 nA/cm² @
 200 V
 - Time schedule = ~5 months
 - Costs of masks ~ 18600 €
 - Sensor cost ~ 930 €/pcs.
 - Prototypes in 2008



BeamCal readout electronics



- Dual-gain front-end electronics: charge amplifier, pulse shaper and T/H circuit
- Successive approximation ADC, one per channel
- Digital memory, 2820 (10 bits + parity) words per channel
- Analog addition of 32 channel outputs for fast feedback; low-latency ADC

Preamplifier & Shaper design



- Preamplifier a voltage amplifier and capacitive feedback
- Two feedback capacitors for different gains



BeamCal electronics: Tentative schedule

- □ April 2007:
- □ July 2007:
- ^O October 2007:
- □ January 2008:
- □ February 2008:
- March 2008:
- □ April 2008:
- July 2008:
- August 2008:
- October 2008:
- January 2009:

High level design complete Charge amplifier designed Filter designed **ADC** designed Memory designed Fast feedback designed Bias and supporting circuits **Circuit layout complete** Verification complete Prototype ready Prototype tests complete



LumiCal readout architecture

- Front-end ASIC will
 contain 32-64 dual
 gain channels
- An ADC will serve
 ~8(1?) front-end
 channels
- First prototypes in
 AMS 0.35 μm



Front-end electronics design



- Charge Sensitive Amplifier +
 PZC + CR-RC Shaper
- First few channel prototype
 ASIC submitted in june 2007



Front-end Layout

Front-end Tests





Front-end Measurements



Pipeline ADC design



- 10 bit pipeline ADC
- □ 1.5 bit per stage
- Fully differential architecture
- Pipeline stages submitted in june 2007





Summary

- The FCAL Collaboration develops the detectors in the very forward region of ILC, independent of a detector concept.
- MC simulations allowed to develop a clear understanding of the physics background, beam-beam effects and the requirements on positioning and precision.
- An intensive R&D acticivity on BeamCal radiation hard sensors is underway. Possible candidades: pCVD diamond (expensive), sCVD (very expensive), rad-hard Si (just starting).
- The design of custom front-end electronics for BeamCal and LumiCal started this year, first prototypes of single components are produced and under test.
- □ A lot of work still to do...